

ABSTRACT OF DISCLOSURE

A microelectronic device and methods of fabricating the same comprising a microelectronic die having an active surface, a back surface, and at least one side. The microelectronic die side comprises a trench sidewall, a lip and a channel sidewall. A 5 metallization layer is disposed on the microelectronic die back surface and the trench sidewall.

AUG 2016 10:30 AM
U.S. PATENT AND TRADEMARK OFFICE
EXAMINER: JEFFREY L. HARRIS
ART UNIT: 2893
TELEPHONE: (571) 272-2893
FAX: (571) 270-1234
MAILING ADDRESS: U.S. PATENT AND TRADEMARK OFFICE
P.O. BOX 1450
WASILLA, AK 99623-1450